IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Dav

David A. Beauchaine, et al.

Appl. No.:

To Be Assigned

Filed:

Concurrently Herewith

For:

SUPPORT FIXTURE FOR SEMICONDUCTOR WAFERS

AND ASSOCIATED FABRICATION METHOD

Mail Stop Patent Application Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT CITATION UNDER 37 C.F.R. § 1.97

Sir:

Attached is a list of documents on form PTO-1449. In accordance with the Office waiver published July 11, 2003, copies of the cited U.S. patents and patent application publications are not enclosed. Applicant does enclose copies of any cited foreign patent documents and non-patent literature in accordance with 37 CFR 1.98(a)(2).

It is requested that the Examiner consider these documents and officially make them of record in accordance with the provisions of 37 C.F.R. § 1.97 and Section 609 of the MPEP. By submitting the listed documents, Applicant in no way makes any admission as to the prior art status of the listed documents, but is instead submitting the listed documents for the sake of full disclosure.

Respectfully submitted,

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Gwen Frickhoeffer

CLT0174642437v1

| Substitute for form 1449/PTO (Revised 04/2003) INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | | | | Complete if Known | | | | |
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| | | | | | Filing Date | | Concurrently Herewith | | |
| | | | | | First Named Inventor | | David A. Beauchaine, et al. | | |
| | | | | | Group Art Unit | | | | |
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| (Use as many sheets as necessary) | | | | | Examiner Name | | 020025/052562 | | |
| Sheet | 1 of 1 | | | | Attorney Docket Number 039035/273763 | | | , | |
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| Examiner | | | | | | | Date | | |
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^{*}Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.